

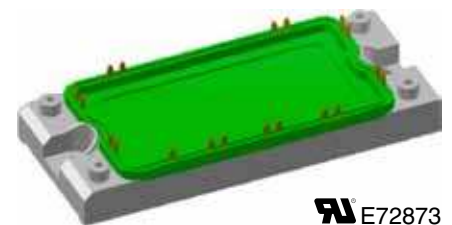
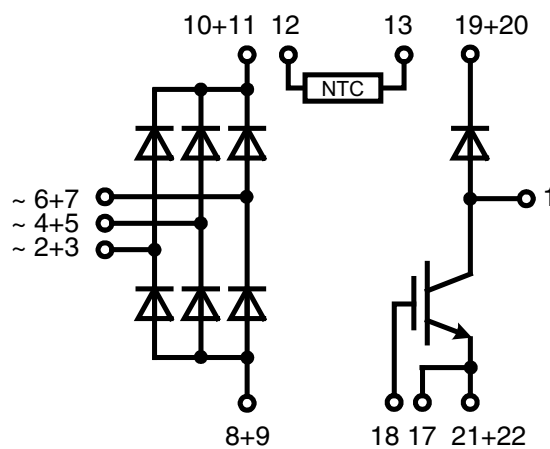
Three Phase Rectifier Bridge

with IGBT and Fast Recovery Diode
for Braking System

Rectifier Diode	Fast Recov. Diode	IGBT
$V_{RRM} = 1600\text{ V}$	$V_{CES} = 1200\text{ V}$	$V_{CES} = 1200\text{ V}$
$I_{dAVM} = 145\text{ A}$	$V_F = 2.75\text{ V}$	$I_{C80} = 108\text{ A}$
$I_{FSM} = 1100\text{ A}$	$I_{FSM} = 200\text{ A}$	$V_{CEsat} = 2.35\text{ V}$

Part name (Marking on product)

VUB145-16NOXT



E72873

Features:

- Soldering connections for PCB mounting
- Convenient package outline
- NTC

Application:

- Drive Inverters with brake system

Package:

- Two functions in one package
- Easy to mount with two screws
- Suitable for wave soldering
- High temperature and power cycling capability
- UL registered, E72873

IGBT

Symbol	Definitions	Conditions	Ratings			Unit	
			min.	typ.	max.		
V_{CES}	collector emitter voltage	$T_{VJ} = 25^{\circ}\text{C}$ to 150°C			1200	V	
V_{GES}	max. DC gate voltage	continuous	-20		+20	V	
V_{GEM}	max. transient collector gate voltage	transient	-30		+30	V	
I_{C25}	collector current	DC			155	A	
I_{C80}		DC			108	A	
P_{tot}	total power dissipation	$T_C = 25^{\circ}\text{C}$			500	W	
$V_{CE(sat)}$	collector emitter saturation voltage	$I_C = 100\text{ A}; V_{GE} = 15\text{ V}$		$T_{VJ} = 25^{\circ}\text{C}$	2.05	2.35	V
$V_{GE(th)}$	gate emitter threshold voltage	$I_C = 4\text{ mA}$	5.4	$T_{VJ} = 25^{\circ}\text{C}$		6.5	V
I_{CES}	collector emitter leakage current	$V_{CE} = V_{CES}; V_{GE} = 0\text{ V}$		$T_{VJ} = 25^{\circ}\text{C}$ $T_{VJ} = 125^{\circ}\text{C}$	0.01 0.1	0.1	mA mA
I_{GES}	gate emitter leakage current	$V_{CE} = 0\text{ V}; V_{GE} = \pm 20\text{ V}$				500	nA
$Q_{G(on)}$	total gate charge	$V_{CE} = 600\text{ V}; V_{GE} = 15\text{ V}; I_C = 100\text{ A}$			295		nC
$t_{d(on)}$	turn-on delay time	inductive load $V_{CE} = 600\text{ V}; I_C = 100\text{ A}$ $V_{GE} = \pm 15\text{ V}; R_G = 6.8\ \Omega; L = 100\ \mu\text{H}$		$T_{VJ} = 125^{\circ}\text{C}$	70		ns
$t_{d(off)}$	turn-off delay time				250		ns
t_r	current rise time				40		ns
t_f	current fall time				100		ns
E_{on}	turn-on energy per pulse				8.5		mJ
E_{off}	turn-off energy per pulse				11.5		mJ
I_{CM}	reverse bias safe operating area	RBSOA; $V_{GE} = \pm 15\text{ V}; R_G = 6.8\ \Omega; L = 100\ \mu\text{H}$			200		A
V_{CEK}		clamped inductive load; $T_{VJ} = 125^{\circ}\text{C}$			$\leq V_{CES} - L_S \cdot di/dt$		V
SCSOA	short circuit safe operating area	$V_{CE} = 720\text{ V}; V_{GE} = \pm 15\text{ V};$ $R_G = 6.8\ \Omega; \text{non-repetitive}$		$T_{VJ} = 125^{\circ}\text{C}$		10	μs
t_{SC}					400		A
I_{SC}						300	A
RBSOA	reverse bias safe operating area	$V_{CE} = 1200\text{ V}; V_{GE} = \pm 15\text{ V};$ $R_G = 6.8\ \Omega; L = 100\ \mu\text{H}; \text{clamped inductive load}$		$T_{VJ} = 125^{\circ}\text{C}$			A
R_{thJC}	thermal resistance junction to case					0.25	K/W
R_{thCH}	thermal resistance case to heatsink				0.1		K/W

Fast Recovery Diode

Symbol	Definitions	Conditions	Ratings			Unit	
			min.	typ.	max.		
V_{RRM}	max. repetitive reverse voltage	$T_{VJ} = 150^{\circ}\text{C}$			1200	V	
I_{FAV}	average forward current	rect.; $d = 0.5$			32	A	
I_{FRMS}	rms forward current	rect.; $d = 0.5$			45	A	
I_{FSM}	max. surge forward current	$t = 10\text{ ms}$			200	A	
P_{tot}	total power dissipation	$T_C = 25^{\circ}\text{C}$			130	W	
V_{F0}	threshold voltage	$T_{VJ} = 150^{\circ}\text{C}$			1.3	V	
r_F	slope resistance	for power loss calculation only			17	m Ω	
V_F	forward voltage	$I_F = 30\text{ A}$		$T_{VJ} = 25^{\circ}\text{C}$	2.75	V	
I_R	reverse current	$V_R = V_{RRM}$		$T_{VJ} = 25^{\circ}\text{C}$ $T_{VJ} = 125^{\circ}\text{C}$		0.25	mA mA
I_{RM}	reverse recovery current	$I_F = 50\text{ A}; V_R = 100\text{ V}; di_F/dt = -100\text{ A}/\mu\text{s}$			8	11	A
t_{rr}	reverse recovery time	$I_F = 1\text{ A}; V_R = 30\text{ V}; di_F/dt = -200\text{ A}/\mu\text{s}$			40		ns
R_{thJC}	thermal resistance junction to case					0.9	K/W
R_{thCH}	thermal resistance case to heatsink				0.3		K/W

 $T_C = 25^{\circ}\text{C}$ unless otherwise stated

Rectifier Diode

Symbol	Conditions	Ratings			Unit
		min.	typ.	max.	
V_{RRM}	max. repetitive reverse voltage			1600	V
I_R	reverse current	$V_R = V_{RRM}$	$T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 150^\circ\text{C}$	0.05 2	mA mA
V_F	forward voltage	$I_F = 150\text{ A}$	$T_{VJ} = 25^\circ\text{C}$	1.68	V
$I_{D(AV)M}$	max. average DC output current	sine; $d = 1/3$; bridge	$T_C = 95^\circ\text{C}$	145	A
V_{F0}	threshold voltage		$T_{VJ} = 150^\circ\text{C}$	0.87	V
r_F	slope resistance	for power loss calculation only		5.9	m Ω
R_{thJC}	thermal resistance junction to case	per diode	$T_{VJ} = 25^\circ\text{C}$	0.5	K/W
R_{thCH}	thermal resistance case to heatsink		$T_{VJ} = 25^\circ\text{C}$	0.1	K/W
P_{tot}	total power dissipation		$T_{VJ} = 25^\circ\text{C}$	250	W
I_{FSM}	max. forward surge current	$t = 10\text{ ms (50Hz)}$ $V_R = 0\text{ V}$	$T_{VJ} = 45^\circ\text{C}$ $T_{VJ} = 150^\circ\text{C}$	1100 960	A A
I^2t	value for fusing	$t = 10\text{ ms (50Hz)}$ $V_R = 0\text{ V}$	$T_{VJ} = 45^\circ\text{C}$ $T_{VJ} = 150^\circ\text{C}$	6050 4610	A ² s A ² s

Temperature Sensor NTC

Symbol	Definitions	Conditions	Ratings			Unit	
			min.	typ.	max.		
R_{25}	resistance		$T_C = 25^\circ\text{C}$	4.75	5.0	5.25	k Ω
$B_{25/85}$					3375		K

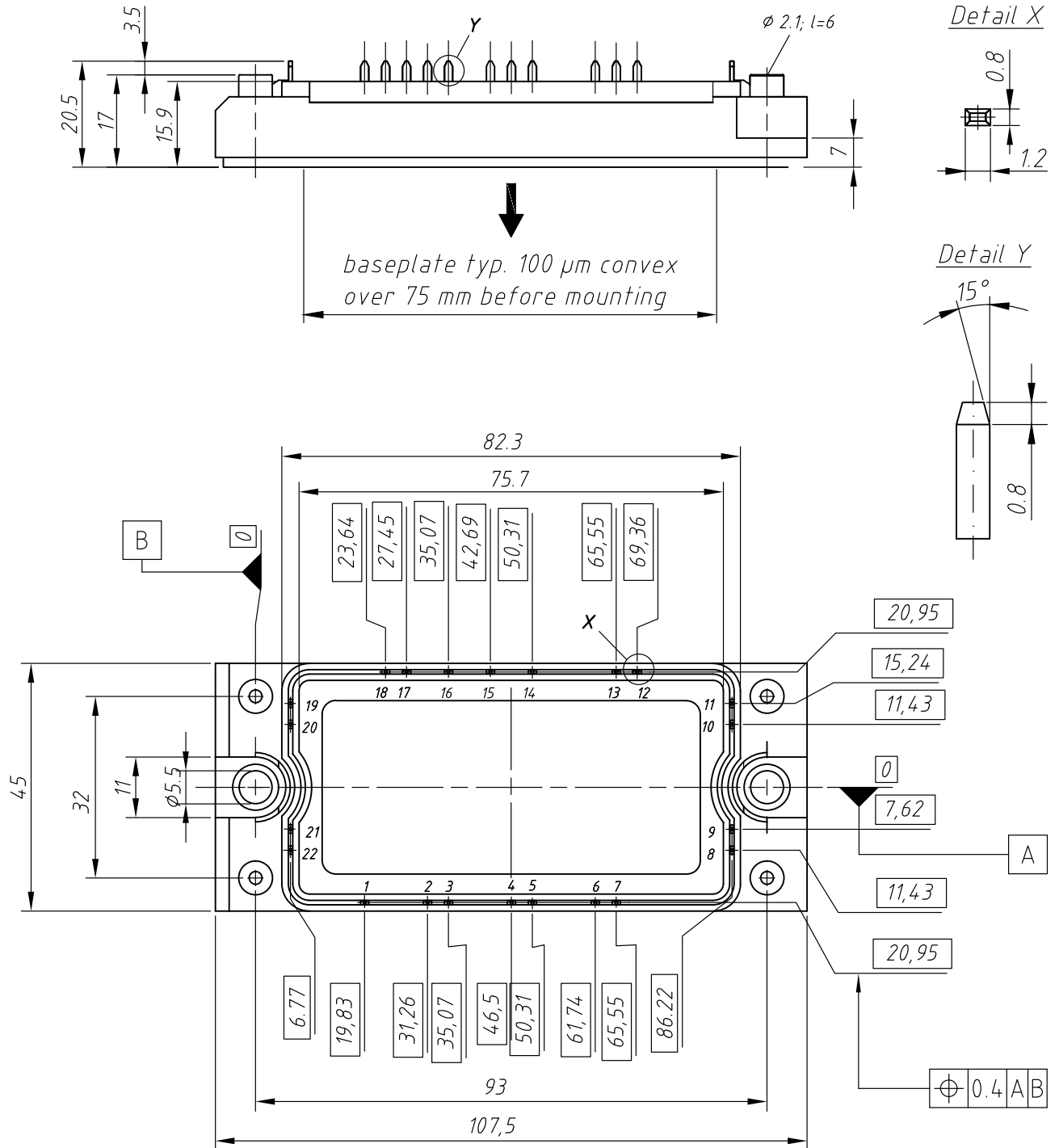
Module

Symbol	Definitions	Conditions	Ratings			Unit
			min.	typ.	max.	
T_{VJ}	operating temperature		-40		125	$^\circ\text{C}$
T_{VJM}	max. virtual junction temperature				150	$^\circ\text{C}$
T_{stg}	storage temperature		-40		125	$^\circ\text{C}$
V_{ISOL}	isolation voltage	$I_{ISOL} \leq 1\text{ mA}; 50/60\text{ Hz};$			3000 3600	V~ V~
M_d	mounting torque	(M5)	3		6	Nm
d_s	creep distance on surface		12.7			mm
d_A	strike distance through air		9.6			mm
a	maximum allowable acceleration				50	m/s ²
$R_{pin-chip}$	thermal resistance pin to chip		$T_{VJ} = 25^\circ\text{C}$	2		m Ω
Weight				180		g

 $T_C = 25^\circ\text{C}$ unless otherwise stated

Outline Drawing

Dimensions in mm (1 mm = 0.0394")



Product Marking

Ordering	Part Name	Marking on Product	Delivering Mode	Base Qty	Ordering Code
Standard	VUB 145-16NOXT	VUB145-16NOXT	Box	6	510475

Rectifier Diode

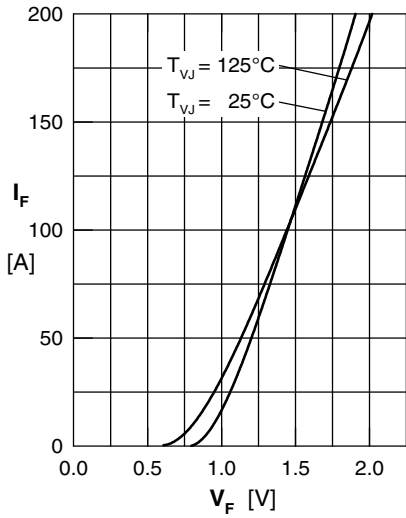


Fig. 1 Typ. forward current vs. voltage drop per diode

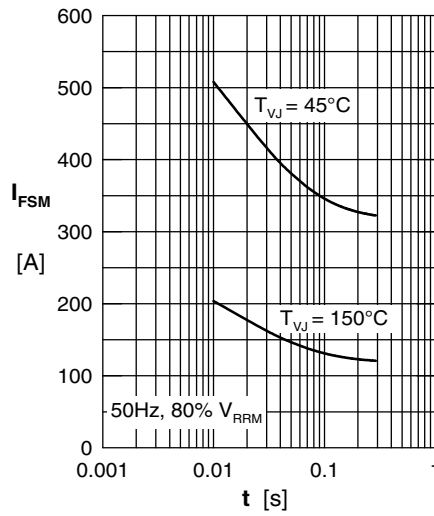


Fig. 2 Surge overload current

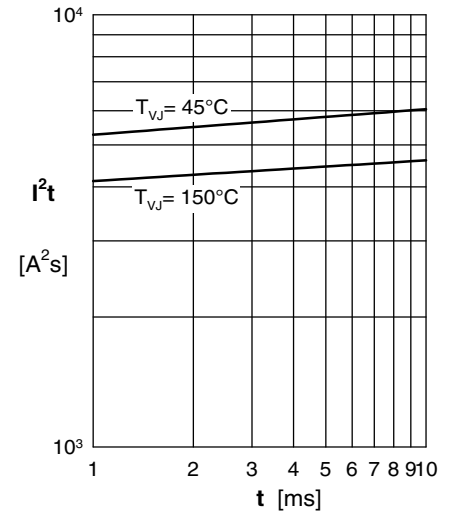


Fig. 3 I^2t versus time per diode

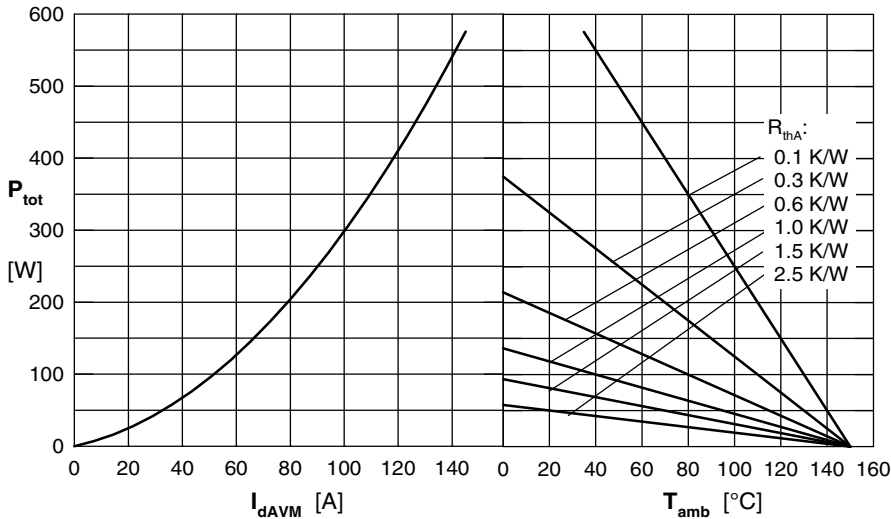


Fig. 4 Typ. power dissipation versus direct output current and ambient temperature, sine 120°

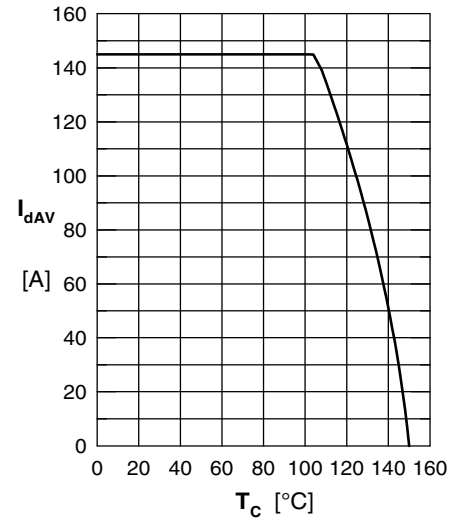


Fig. 5 Max. forward current vs. case temperature

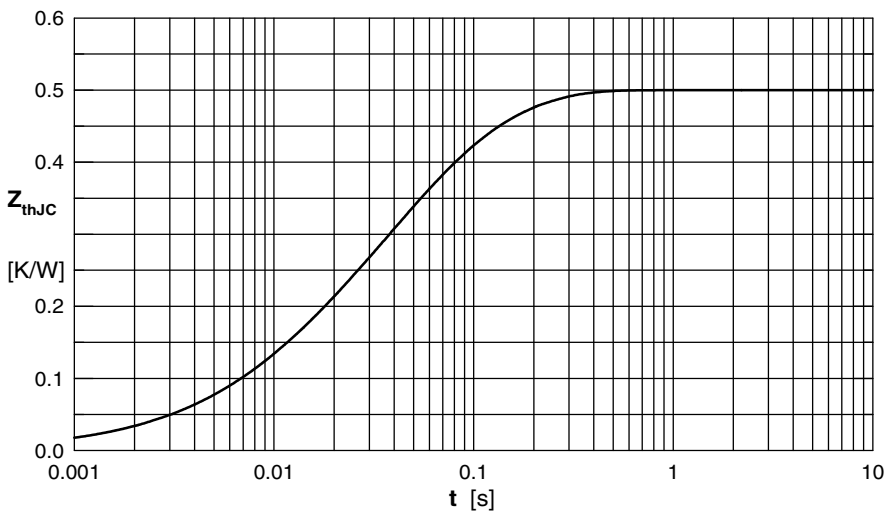


Fig. 6 Typ. transient thermal impedance junction to case

IXYS reserves the right to change limits, test conditions and dimensions.

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IGBT

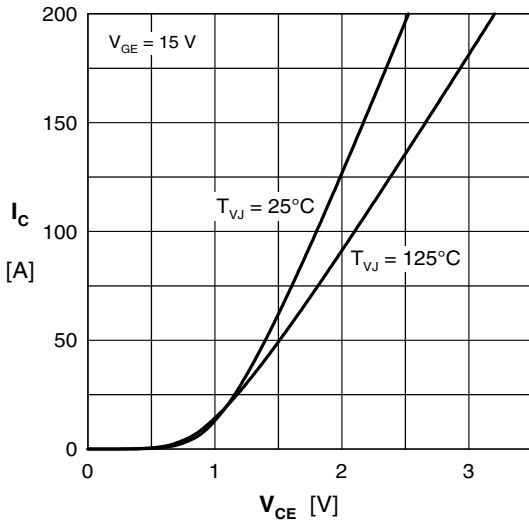


Fig. 1 Typ. output characteristics on die level

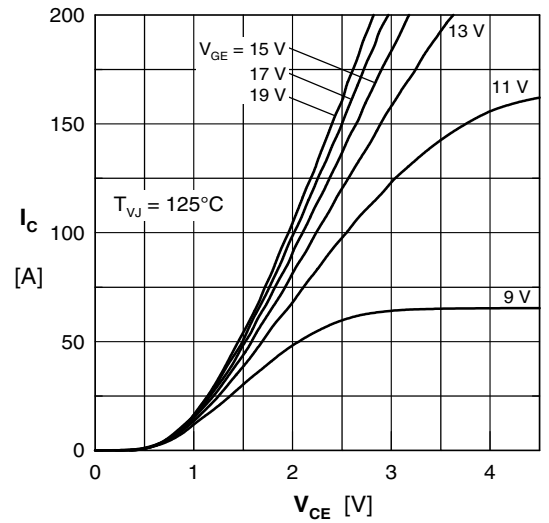


Fig. 2 Typ. output characteristics on die level

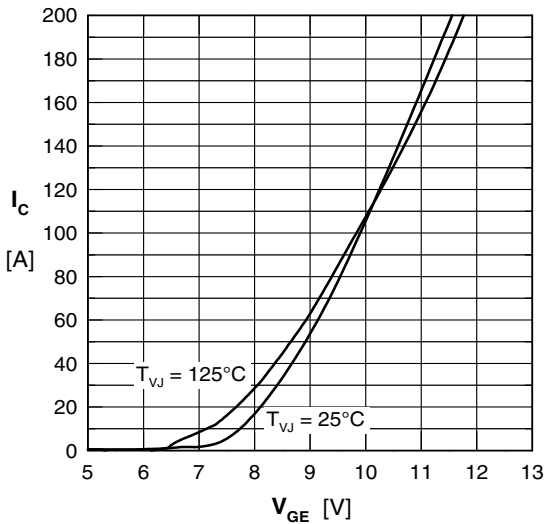


Fig. 3 Typ. transfer characteristics

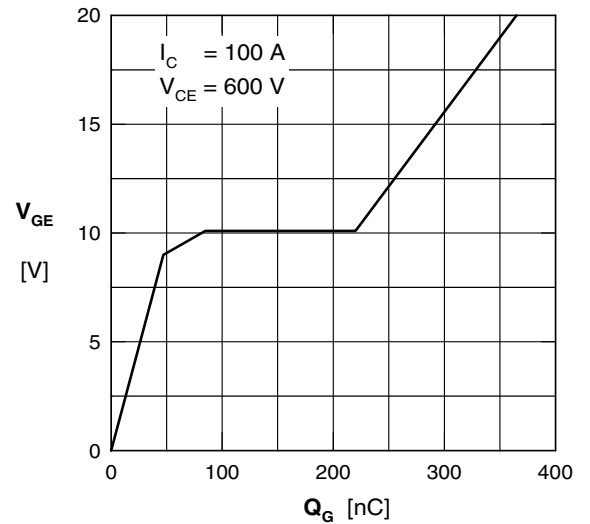


Fig. 4 Typ. turn-on gate charge

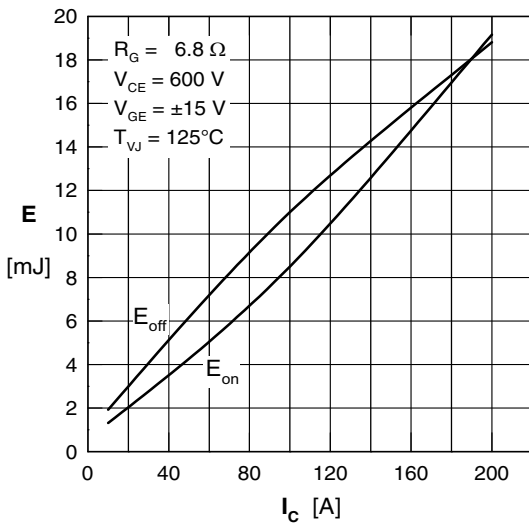


Fig. 5 Typ. switching energy vs. collector current

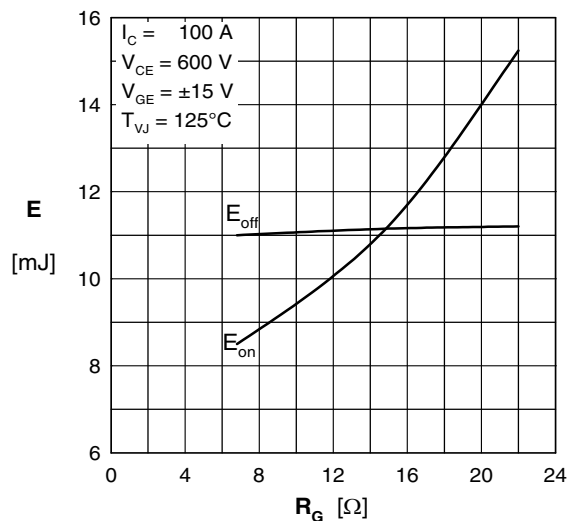


Fig. 6 Typ. switching energy vs. gate resistance

Fast Recovery Diode

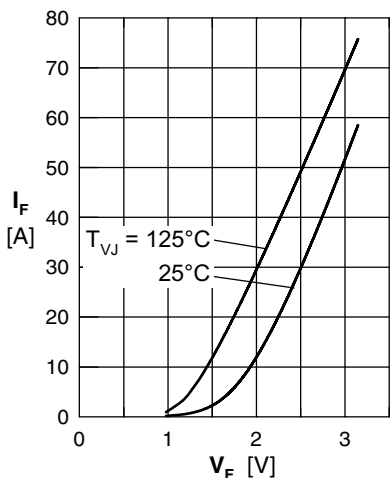


Fig. 1 Typ. forward current I_F vs. V_F

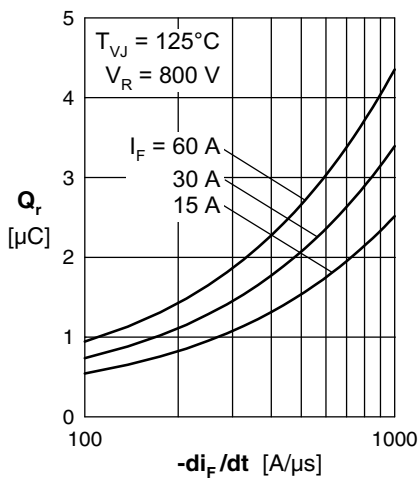


Fig. 2 Typ. reverse recovery charge Q_r versus $-di_F/dt$

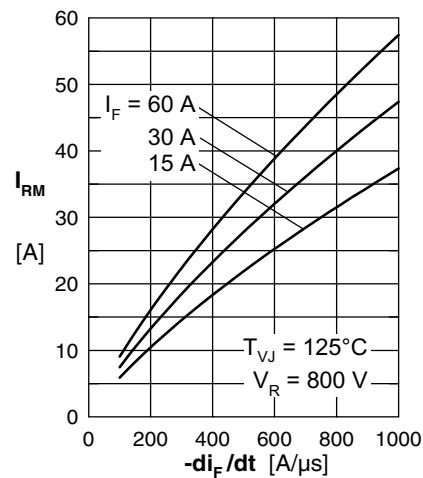


Fig. 3 Typ. peak reverse current I_{RM} versus $-di_F/dt$

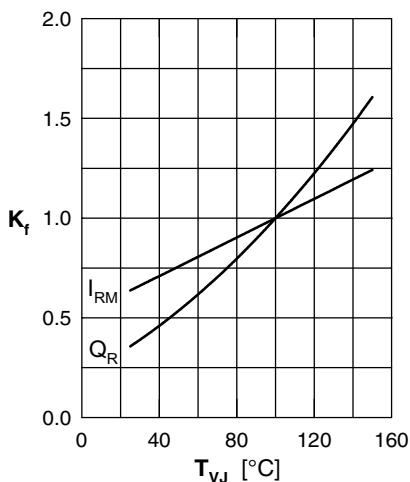


Fig. 4 Typ. dynamic parameters Q_r , I_{RM} , versus T_{VJ}

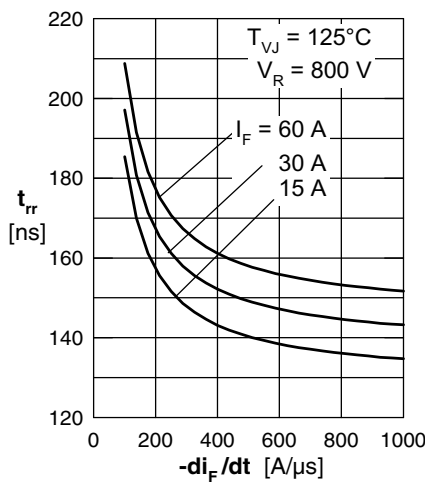


Fig. 5 Typ. recovery time t_{rr} vs. $-di_F/dt$

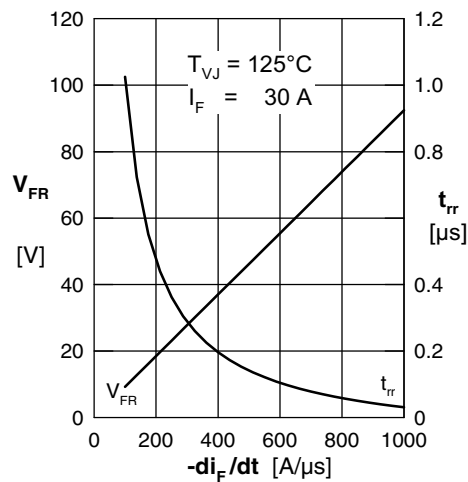


Fig. 6 Typ. peak forward voltage V_{FR} and t_{rr} versus di_F/dt

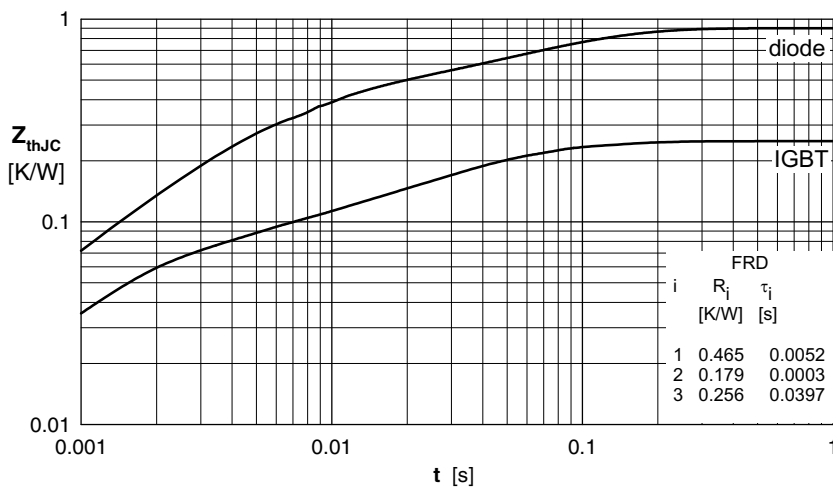


Fig. 7 Typ. transient thermal impedance junction to case

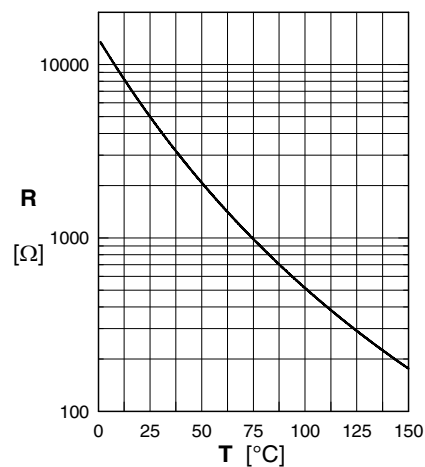


Fig. 8 Typ. thermistor resistance versus temperature